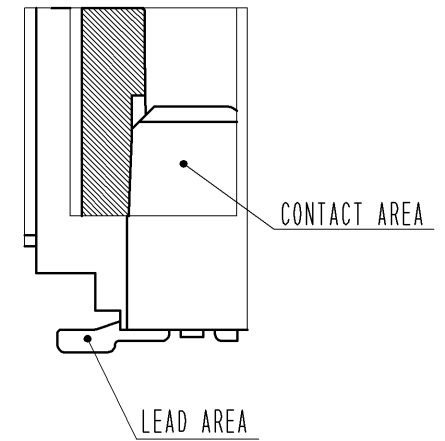


A (10:1)



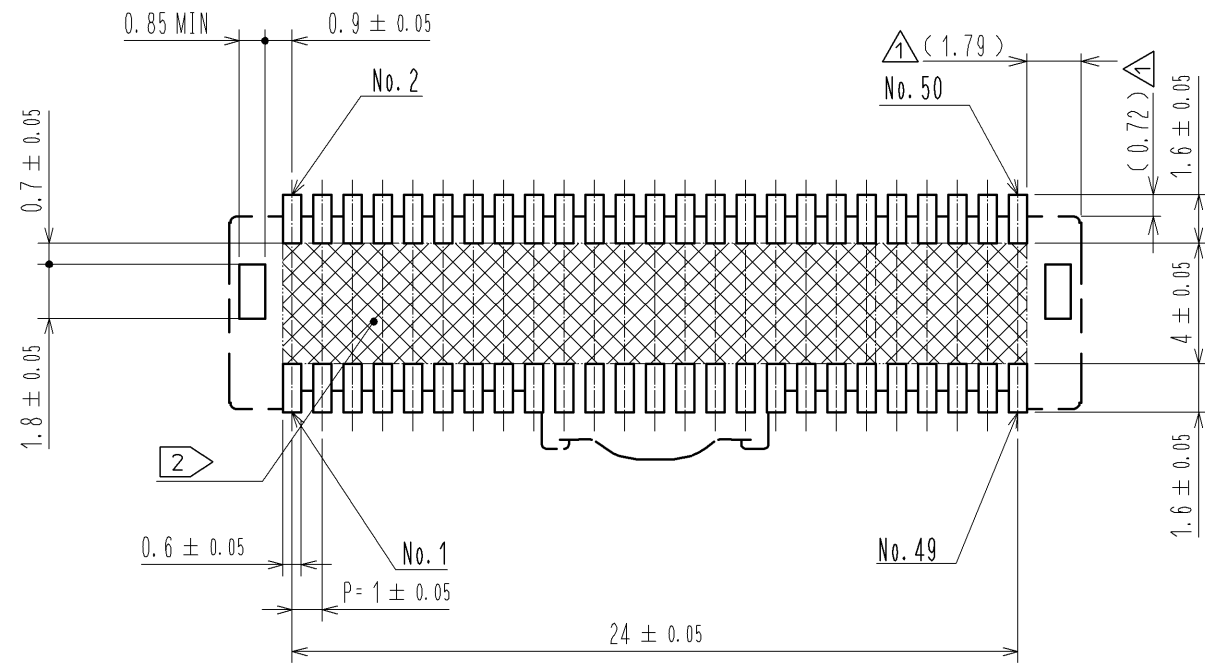
- NOTES
1. LEAD CO-PLANARITY SHALL BE 0.1 mm MAX.
 2. AREA INDICATED MUST BE FREE OF CONDUCTIVE TRACES OR THE CONDUCTIVE TRACES MUST BE COVERED BY RESIST FILM.
 3. PLEASE CONSULT HIROSE WHEN THE PRODUCT IS MOUNTED TO FPC.

NO.	MATERIAL	FINISH . REMARKS	NO.	MATERIAL	FINISH . REMARKS
3	BRASS	CONTACT AREA : Au PLATING 0.05µm MIN. LEAD AREA : Au PLATING 0.05µm MIN. UNDERPLATING : Ni PLATING 1µm MIN.	8	PS	REEL, BLACK
2	BRASS	CONTACT AREA : Au PLATING 0.05µm MIN. LEAD AREA : Au PLATING 0.05µm MIN. UNDERPLATING : Ni PLATING 1µm MIN.	7	POLYESTER	CLEAR
1	LCP	BLACK, UL94V-0	6	PS	CLEAR
			5	STAINLESS STEEL	-
			4	BRASS	SURFACE : Sn PLATING 1µm MIN. UNDERPLATING : Ni PLATING 0.5µm MIN.

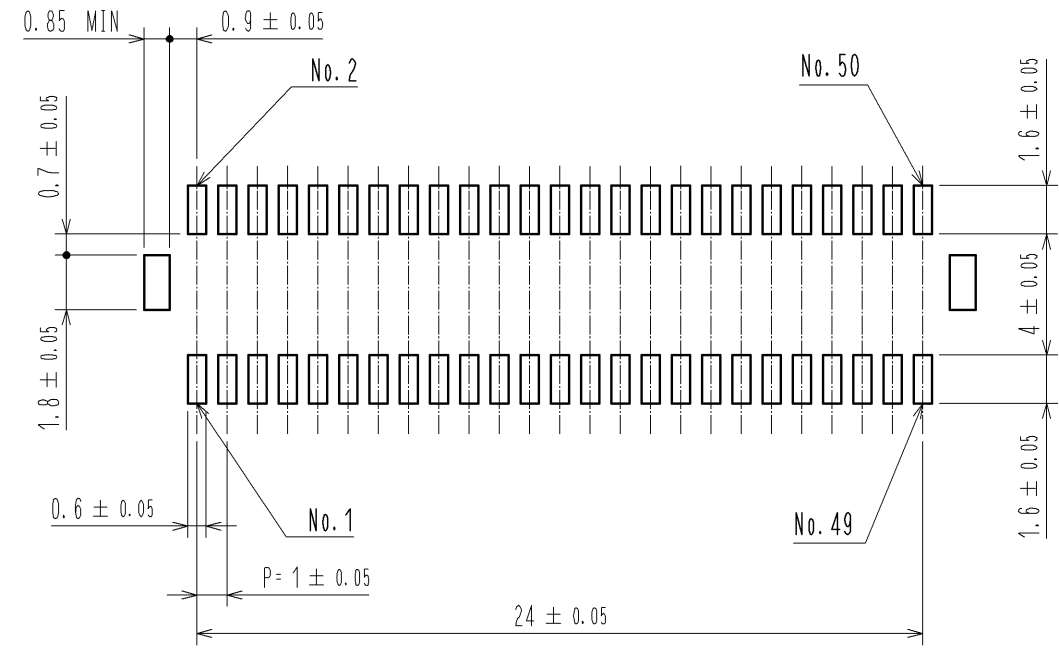
UNITS	SCALE	COUNT	DESCRIPTION OF REVISIONS	DESIGNED	CHECKED	DATE
mm	FREE	4	DIS-H-007735	MI. SAKIMURA	TS. KUMAZAWA	13. 03. 22

HRS HIROSE ELECTRIC CO., LTD.	APPROVED : KI. AKIYAMA	12. 05. 31	DRAWING NO.	EDC3-330237-01
	CHECED : HK. UMEHARA	12. 05. 31	PART NO.	DF50-50DP-1V(51)
	DESIGNED : TT. OHSAKO	12. 05. 30	CODE NO.	CL665-0011-1-51
	DRAWN : TT. OHSAKO	12. 05. 30		

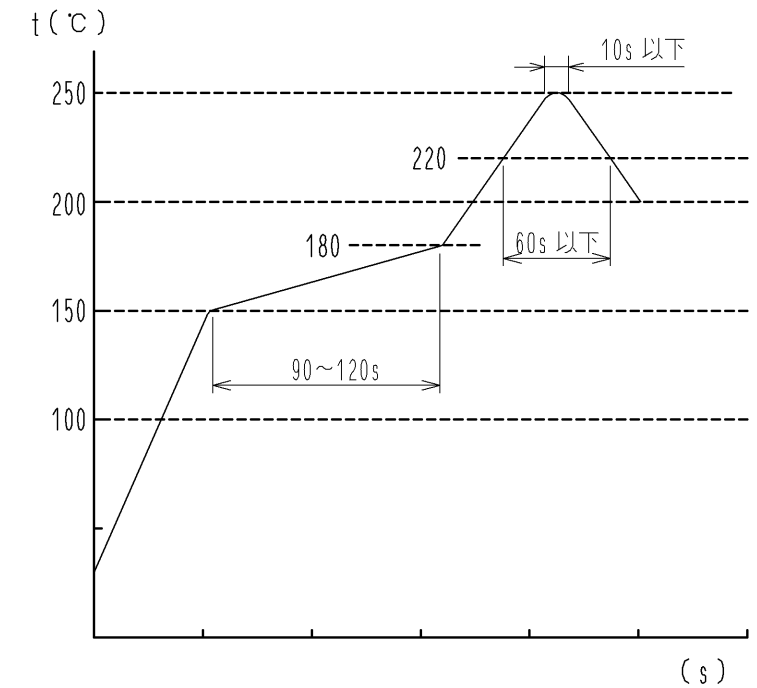
RECOMMENDED PCB LAYOUT
(MOUNTING SURFACE SIDE) (FREE)



RECOMMENDED METAL MASK (FREE)
THICKNESS : 0.1mm



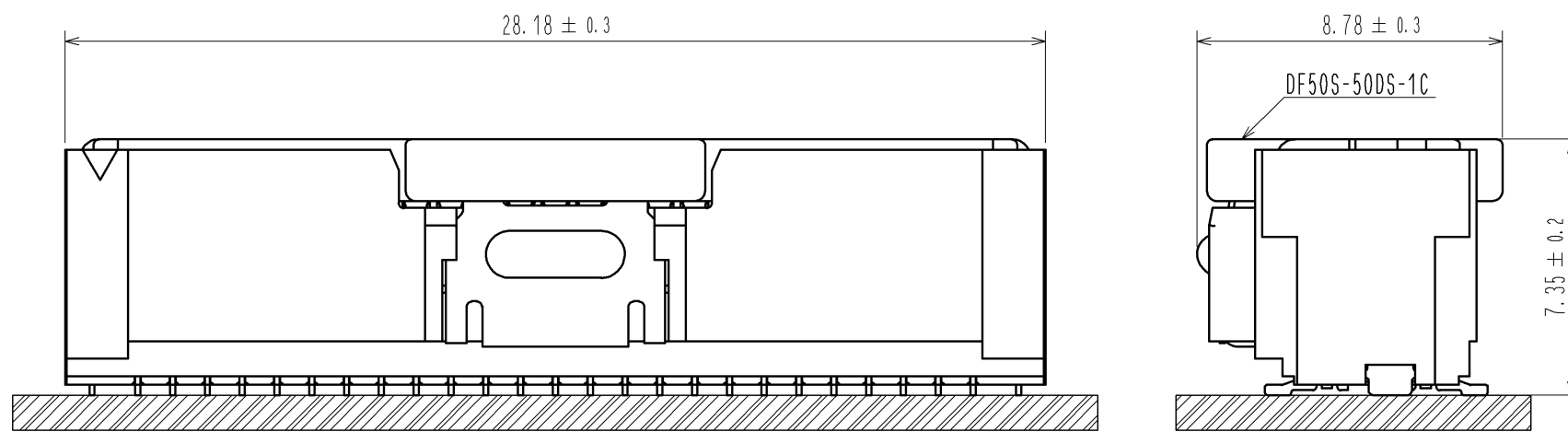
REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE(REFERENCE)



NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
THE TEMPERATURE OF THIS PROFILE IS MASURED ON THE LEAD TERMINAL.

WE RECOMMEND PERFORMING AN EVALUATION UNDER THE MOUNTING
CONDITIONS YOU WILL BE USING BECAUSE IT COULD BE AFFECTED
BY ANY CONDITION:TYPE OF SOLDER PASTE, SIZE OF PCB, MOUNTING
METAL etc.

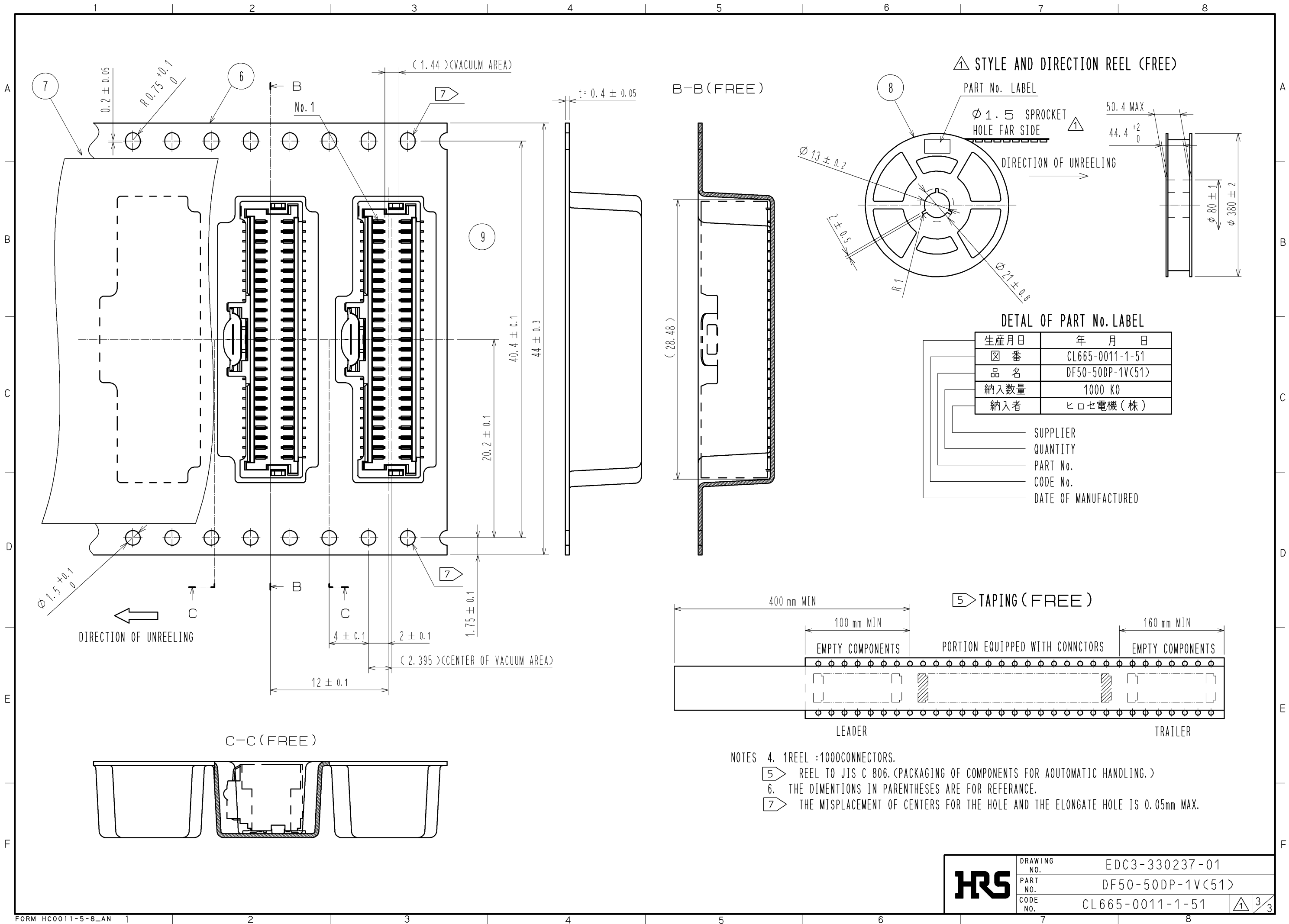
MATING FIGURE (5 : 1)



HRS

DRAWING NO.	EDC3-330237-01
PART NO.	DF50-50DP-1V(51)
CODE NO.	CL665-0011-1-51

2/3



HRS	DRAWING NO.	EDC3-330237-01
	PART NO.	DF50-50DP-1V(51)
	CODE NO.	CL665-0011-1-51
		3/3